



Material Content Data Sheet



Sales Product Name	ESD5V3L1B-02LS E6327			Issued		29. August 2013		
MA#	MA000951796							
Package	PG-TSSLP-2-1			Weight*		0.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.23		2341	
	noble metal	gold	7440-57-5	0.001	0.91		9068	
	inorganic material	silicon	7440-21-3	0.010	6.72	7.86	67210	78619
leadframe	non noble metal	nickel	7440-02-0	0.036	24.39	24.39	243910	243910
wire	noble metal	gold	7440-57-5	0.002	1.64	1.64	16405	16405
encapsulation	organic material	carbon black	1333-86-4	0.001	0.58		5835	
	plastics	epoxy resin	-	0.012	7.88		78786	
	inorganic material	silicondioxide	60676-86-0	0.074	49.90	58.36	498980	583601
leadfinish	noble metal	gold	7440-57-5	0.004	2.76	2.76	27586	27586
plating	noble metal	silver	7440-22-4	0.007	4.99	4.99	49879	49879
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com